



## Material Content Data Sheet



<b>Sales Product Name</b>		SPD18P06P G		<b>Issued</b>		22. January 2018		
<b>MA#</b>		MA001726328						
<b>Package</b>		PG-TO252-3-311		<b>Weight*</b>		313.98 mg		
Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]
chip	inorganic material	silicon	7440-21-3	2.472	0.79	0.79	7872	7872
leadframe	inorganic material	phosphorus	7723-14-0	0.043	0.01		137	
	non noble metal	iron	7439-89-6	0.143	0.05		456	
	non noble metal	copper	7440-50-8	143.098	45.58	45.64	455749	456342
	non noble metal	aluminium	7429-90-5	1.046	0.33	0.33	3332	3332
wire	inorganic material	antimonytrioxide	1309-64-4	1.987	0.63		6329	
encapsulation	plastics	brominated resin	-	2.129	0.68		6782	
	organic material	carbon black	1333-86-4	2.271	0.72		7234	
	plastics	epoxy resin	-	19.164	6.10		61033	
	inorganic material	silicondioxide	60676-86-0	116.401	37.07	45.20	370722	452100
leadfinish	non noble metal	tin	7440-31-5	3.740	1.19	1.19	11912	11912
plating	inorganic material	phosphorus	7723-14-0	0.000	0.00		1	
	non noble metal	nickel	7440-02-0	0.086	0.03	0.03	275	276
solder	non noble metal	tin	7440-31-5	0.044	0.01		140	
	noble metal	silver	7440-22-4	0.055	0.02		175	
	non noble metal	lead	7439-92-1	2.102	0.67	0.70	6694	7009
heatspreader	inorganic material	phosphorus	7723-14-0	0.006	0.00		18	
	non noble metal	iron	7439-89-6	0.019	0.01		61	
	non noble metal	copper	7440-50-8	19.177	6.11	6.12	61078	61157
*deviation	< 10%		Sum in total:			100.00		1000000

### Important Remarks:

1. Infineon Technologies AG provides full material declaration based on information provided by third parties and has taken and continues to take reasonable steps to provide representative and accurate information.
2. Infineon Technologies AG and Infineon Technologies AG suppliers consider certain information to be proprietary, and thus CAS numbers and other limited information may not be available for release.
3. All statements are based on our present knowledge, are provided 'as is' and may be subject to change at any time due to technical requirements and development without notification.

This product is in compliance with EU Directive 2015/863/EU amending Annex II to EU Directive 2011/65/EU (RoHS) and contains Pb according RoHS exemption 7a, Lead in high melting temperature type solders.

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